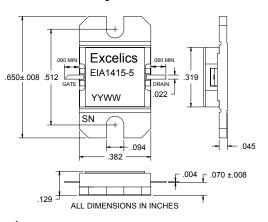


UPDATED 11/17/2006

14.40-15.35GHz 5-Watt Internally Matched Power FET

FEATURES

- 14.40-15.35GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression •
- 7.0 dB Power Gain at 1dB Compression •
- 33% Power Added Efficiency •
- Hermetic Metal Flange Package •
- 100% Tested for DC, RF, and R_{TH}



EIA1415-5

ELECTRICAL CHARACTERISTICS ($T_a = 25^{\circ}C$)

ELECTRICAL CHARACTERISTICS ($T_a = 25^{\circ}C$) Caution! ESD sensitive device.							
SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	ТҮР	MAX	UNITS		
P _{1dB}	Output Power at 1dB Compression f =14.40-5.35GHz V_{DS} = 8 V, $I_{DSQ} \approx$ 1400mA	35.5	36.5		dBm		
G _{1dB}	Gain at 1dB Compressionf = 14.40-15.35GHz V_{DS} = 8 V, $I_{DSQ} \approx 1400$ mA	6.0	7.0		dB		
∆G	Gain Flatness f =14.40-15.35GHz V _{DS} = 8 V, I _{DSQ} ≈ 1400mA			±0.6	dB		
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 8 \text{ V}, I_{DSQ} \approx 1400 \text{mA}$ f =14.40-15.35GHz		33		%		
Id _{1dB}	Drain Current at 1dB Compression f =14.40-15.35GHz		1700	2000	mA		
I _{DSS}	Saturated Drain Current $V_{DS} = 3 V, V_{GS} = 0 V$		2880	3600	mA		
V _P	Pinch-off Voltage V_{DS} = 3 V, I_{DS} = 29 mA		-1.0	-2.5	V		
R _{TH}	Thermal Resistance ²		5.5	6.0	°C/W		

Note: 1) Tested with 100 Ohm gate resistor.

2) Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING^{1,2}

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
V _{DS}	Drain-Source Voltage	10	8V
V _{GS}	Gate-Source Voltage	-5	-3V
lgf	Forward Gate Current	43.2mA	14.4mA
lgr	Reverse Gate Current	-7.2mA	-2.4mA
Pin	Input Power	35.5dBm	@ 3dB Compression
Tch	Channel Temperature	175 °C	175 °C
Tstg	Storage Temperature	-65 to +175 °C	-65 to +175 °C
Pt	Total Power Dissipation	25W	25W

Note: 1) Exceeding any of the above ratings may result in permanent damage.

2) Exceeding any of the above ratings may reduce MTTF below design goals.



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14.40-15.35GHz 5-Watt Internally Matched Power FET

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness